

DMG48480F021_01WTCZG2

Features:

- Powered by T5L0 ASIC, running DGUS II HMI platform.
- 2.1 inch, 480*480 resolution, IPS-TFT LCD, Circular LCD screen.
- LCD and TP optical bonding process, with high structural reliability.
- With enclosure, self-locking installation structure.



1. External interface



PIN	Definition	I/O	Functional Description
1	+5V	I	Power supply, DC4.5-5.5V.
2	+5V	I	
3	GND	GND	GND
4	GND	GND	
5	GND	GND	
6	AD7	I	5 input ADCs. 12-bit resolution in case of 3.3V power supply. 0-3.3V input voltage. Except for AD6, the rest data is sent to OS core via UART3 in real time with 16KHz sampling rate. AD1 and AD5 can be used in parallel, and AD3 and AD7 can be used in parallel, which equals to two 32KHz sampling AD. AD1, AD3, AD5, AD7 can be used in parallel, which equals to a 64KHz sampling AD; the data is summed 1024 times and then divided by 64 to obtain a 64Hz 16bit AD value by oversampling.
7	AD6	I	
8	AD5	I	
9	AD3	I	
10	AD1	I	
11	+3.3	O	3.3V output, maximum load of 150mA.
12	SPK	O	External MOSFET to drive buzzer or speaker. The external 10K resistor should be pulled down to the ground to ensure that power-on is low level.
13	SD_CD	IO	SD/SDHC interface, The SD_CD connects a 22pF capacitor to GND near the SD card interface.
14	SD_CK	O	
15	SD_D3	IO	
16	SD_D2	IO	
17	SD_D1	IO	
18	SD_D0	IO	

19	PWM0	O	2 16-bit PWM output. The external 10K resistor should be pulled down to the ground to ensure that power-on is low level. The OS core can be controlled in real time via UART3.
20	PWM1	O	
21	P3.3	IO	If using RX8130 or SD2058 I2C RTC to connect to both IOs, SCL should be connected to P3.2, and SDA connected to P3.3 in parallel with 10K resistor pull-up to 3.3V.
22	P3.2	IO	
23	P3.1/EX1	IO	It can be used as an external interrupt 1 input at the same time, and supports both low voltage level or trailing edge interrupt modes.
24	P3.0/EX0	IO	It can be used as an external interrupt 0 input at the same time, and supports both low voltage level or trailing edge interrupt modes.
25	P2.7	IO	IO interface
26	P2.6	IO	IO interface
27	P2.5	IO	IO interface
28	P2.4	IO	IO interface
29	P2.3	IO	IO interface
30	P2.2	IO	IO interface
31	P2.1	IO	IO interface
32	P2.0	IO	IO interface
33	P1.7	IO	IO interface
34	P1.6	IO	IO interface
35	P1.5	IO	IO interface
36	P1.4	IO	IO interface
37	P1.3	IO	IO interface
38	P1.2	IO	IO interface
39	P1.1	IO	IO interface
40	P1.0	IO	IO interface
41	UART4_TXD	O	UART4
42	UART4_RXD	I	
43	UART5_TXD	O	UART5
44	UART5_RXD	I	
45	P0.0	IO	IO interface
46	P0.1	IO	IO interface
47	CAN_TX	IO	CAN interface (External CAN chip drive is required. See 5-(6) for circuit reference)
48	CAN_RX	IO	
49	UART2_TXD	O	UART2 (UART0 serial port of OS core)
50	UART2_RXD	I	

2. Specification parameters

2.1 Product parameters

Main Chip	T5L0
User Interface	50Pin_0.5mm FPC
FLASH	8M Bytes
UI Version	DGUS II / TA
Debugging Tools	Adapter board power supply
Size	2.1 inch
Resolution	480*480
Active Area (AA)	D=53.28mm
Viewing Area (VA)	D=53.88mm
Viewing Angle	Wide viewing angle, typical value of 85°/85°/85°/85°(L/R/U/D)
Backlight Service Life	>10,000 hours
Brightness	300nit
Brightness Control	100-level brightness adjustment (Flickering may occur at 1%-30% of max brightness; not recommended for use in this range)
Note: Use dynamic screen saver to prevent afterimages from prolonged fixed page display.	
Type	Capacitive touch panel
Structure	G+FF structure with tempered glass surface and hardness ≥6H
Light Transmittance	>85%

2.2 Interface parameters

Item	Conditions	Min	Typ	Max	Unit
Baud Rate	User Set(Configure the CFG file)	3150	115200	3225600	bps
Output Voltage(TXD)	Output 1	3.0	3.3	-	V
	Output 0	-	0	0.3	V
Input Voltage(RXD)	Input 1	-	-	3.3	V
	Input 0	0	-	0.5	V
Interface	UART2: TTL; UART4: TTL; (Only available after OS configuration) UART5: TTL; (Only available after OS configuration)				
Data Format	UART2: N81; UART4: N81/E81/O81/N82; 4 modes (OS configuration) UART5: N81/E81/O81/N82; 4 modes (OS configuration)				

2.3 Electrical specifications

Rated Power	<2W	
Operating Voltage	4.5-5.5V, typical value of 5V.	
Operating Current	144mA	VCC=5V, max backlight.
Recommended power supply: 5V 0.5A DC		

2.4 Operating environment

Operating Temperature	-10℃ to 60℃ (5V @ 60% RH)
Storage Temperature	-20℃ to 70℃
Operating Humidity	10%-90%RH, typical value of 60% RH.

3. Reliability test

3.1 Electrostatic discharge test

Test temperature: 25°C. Test humidity: 50%RH.

Test process: Place the product on the test bench fixture (approximately 15cm in height), and perform contact and air discharge tests on the smart LCM. Observe if any freezing, black or white screen, flickering, or rebooting occurs during the test.

Test conclusion: The product's ESD performance meets GB/T 17626.2 Class B standards.

Discharge Type	Discharge Value	Result
Air discharge	±8KV	Normal operation

3.2 High and low temperature test

Test temperature:-20~70°C.

Test process: the product will be placed obliquely in the high and low temperature test chamber for 12h for 20 on and off cycles. Then it will be check at room temperature after power on for the appearance and function, CTP offset situation, jumping point, page random switching and failure.

Temperature	Result
High temperature(70°C)	Normal operation
Low temperature(-20°C)	Normal operation

4. T5L0 ASIC

T5L0 ASIC is a low-power, cost-effective, GUI and application highly integrated single-chip dual-core ASIC designed by DWIN Technology for small-size LCD and mass produced in 2020.

(1) Mature and stable 8051 core which is the most widely used with the maximum operating frequency of T5L is up to 250MHz, 1T(single instruction cycle)high speed operation.

(2) Separate GUI CPU core running DGUS II System:

- High-speed display memory, 2.4GB/S bandwidth. 18-bit color display resolution support up to 1024*768 (TA mode), 854*480 (DGUS mode).
- 2D hardware acceleration and the UI with animation and icons as its main feature is extremely cool and smooth.
- Images and icons stored in JPEG format. Adopt Low-cost 16Mbytes SPI Flash.
- High quality ratio and sound restoration and playback.
- 128Kbytes variable storage space for exchanging data with OS CPU Core and memory.
- 2 10-bit 800KHz DC/DC controllers simplify LED backlight, analog power design and save cost and space.
- Support DGUS development and simulation on PC. Support backend remote upgrade.

(3) Separate CPU (OS CPU) core runs user 8051 code or DWIN OS system and user CPU is omitted in practical application:

- Standard 8051 core and instruction set, 64Kbytes code space, 32Kbytes on-chip RAM.
- 64-bit integer mathematical operation unit (MDU), including 64-bit MAC and 64-bit divider.
- Built-in software WDT, 3 16-bit Timers, 12 interrupt signals support up to four levels of interrupt nesting.
- Support IAP online simulation and debugging with unlimited breakpoints.
- Upgrade code online through DGUS system.

(4) 1Mbytes on-chip Flash with DWIN patent encryption technology ensure code and data security.

(5) Operating temperature ranges from -40°C to +85°C (IC operating temperature customizable from -55°C to 105°C).

Low power consumption and strong anti-interference ability. It can work stably on double-sided PCB and passes EMC/EMI test easily.

5. COF Screen Secondary Development

Standard 8051 core, easy to develop in C language and assembly language.

(1) 22 IOs:

To use output function of IO, you need to open the output control, output strength and peripheral multiplexing power-on initialization configuration. Subsequent use of IO is consistent with the standard 8051 as follows.

```
#include "sys.h"
sbit LED1 = P1^0;
sbit KEY1 = P1^1;
//IOPin initialization
void io_init()
{
    PORTDRV = 0x01;//Driving current is 8mA
    P1MDOUT |= 0x01;//Set P1.0 as output to drive LED1 light
    P1MDOUT &= 0xFD;//Set P1.1 as input to read the voltage level change of the pin
}
void main(void)
{
    u16 cnt_1ms;
    u16 key1_sta;//Store the voltage level state of the KEY1 pin
    sys_init();//System initialization
    io_init();//IOPin initialization
    cnt_1ms = 0;
    key1_sta = KEY1;
    while(1)
    {
        cnt_1ms++;
        sys_delay_ms(1);//Delay sub-function, LED1 blinks every 500ms.
        if(cnt_1ms==500)
        {
            LED1 = !LED1;
            cnt_1ms = 0;
        }
        //If the voltage level of the pin has changed, it will be updated in the interface
        if(key1_sta!=KEY1)
        {
            key1_sta = KEY1;
            sys_write_vp(0x1000,(u8*)&key1_sta,1);
        }
    }
}
```

(2) 3 UARTs:

High-speed serial port, supporting up to 3225600bps, as follows.

```
#include "sys.h"
#include "uart2.h"
void main(void)
{
    u16 len;
    sys_init();/System initialization
    uart2_init(115200);/Initialize serial port 2
    while(1)
    {
        if(uart2_rx_sta&UART2_PACKET_OK)//Received serial packet
        {
            len = uart2_rx_sta&UART2_PACKET_LEN;//Get the length of the serial packet without "\r\n" or '\n' terminator
            uart2_buf[len++] = 0;//Add 2 empty strings at the end
            uart2_buf[len++] = 0;
            printf("T5L_C51:%s\r\n",uart2_buf);//Return the received packet to the sender with the prefix "T5L_C51:"
            sys_write_vp(0x2000,uart2_buf,len/2+1);//At the same time display the packet to the interface
            uart2_rx_sta = 0;//Reset means that this serial port packet has been processed
        }
    }
}
```

(3) 1 CAN:

Only the special function registers of the CAN need to be configured as follows.

```
void CanInit()
{
    P0MDOUT = 0x04;    //P0.2(CAN_TX) is configured as output
    P0 = 0xFF;        //Output high voltage level
    ADR_H = 0xFF;     //Configuring DGUS variable memory addresses
    ADR_M = 0x00;
    ADR_L = 0x60;
    ADR_INC = 1;     //Configure address increments
    RAMMODE = 0x8F;  // Write mode
    while(!APP_ACK); //Waiting for confirmation,
    Among answers of Hardware to 8051 occupied variable memory request, 1=OK and 0=BUSY, which need to continue to wait.
    DATA3 = 0x1A;   //Variable memory address 0xFF:0060 assignment
    DATA2 = 0x17;
    DATA1 = 0x0F;
    DATA0 = 0;
    APP_EN = 1;
    while(APP_EN);  //Wait for the data operation to be completed, and reset after the operation is completed
    DATA3 = 0;     // Acceptance register 0xFF:0061 assignment reset
    DATA2 = 0;
    DATA1 = 0;
    DATA0 = 0;
    APP_EN = 1;
    while(APP_EN); //Wait for the data operation to be completed, and reset after the operation is completed
    DATA3 = 0xFF; //Acceptance Mask Register 0xFF:0062 all set to 1, and no acceptance of reception
    DATA2 = 0xFF;
    DATA1 = 0xFF;
    DATA0 = 0xFF;
    APP_EN = 1;
    while(APP_EN); //Wait for the data operation to be completed, and reset after the operation is completed
    RAMMODE = 0;   //Terminate access to DGUS variable memory
    CAN_CR = 0xA0; //Open CAN and configure FF0060-FF0062
    while(CAN_CR&0x20); //Execute the configuration of FF0060-FF0062
    ECAN = 1;     //Open the CAN interrupt
    EA = 1;      //Open the total interrupt
}
```

(4) 5 A/Ds: 12-bit, supports sampling to 16-bit.

Only the special function registers of the A/Ds need to be configured as follows.

```
#include "sys.h"
#include "adc.h"
void main(void)
{
    u16 ad;
    float vol;
    sys_init();//System initialization
    while(1)
    {
        ad = adc_read_avg(ADC_CHANNEL0,10);//1.Read the ad value of channel 0
        vol = ad*(3300.0f/4095);//2.Calculate the voltage in mV
        sys_write_vp(0x2000,(u8*)&ad,1);//Update the ad value
        sys_write_vp(0x2001,(u8*)&vol,2);//Update the voltage value
    }
}
```

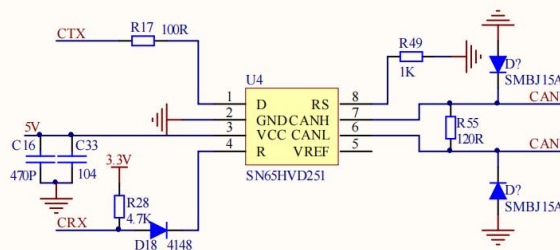
(5) 2 PWMs: 16-bit high accuracy, adjustable resolution.

Only need to configure the frequency and duty cycle of PWM as follows.

```
void Pwm_0()
{
    u8 i=0;
    u8 temp[6]={0xAA,0x20,0x42,0x56,0x78,0};//Configure the duty cycle of pwm_0 to 100%
    Write_Dgus(0x87,0x2042);//Configure the frequency to 100khz
    Write_Dgus(0x86,0x5A01);//
    for(i=0;i<5;i++) //Calculate the checksum
        temp[5]+=temp[i];
    for(i=0;i<6;i++)//Configure the duty cycle
        OneSendData3(temp[i]);
}
```

(6) CAN circuit design parameters.

CAN_SN65HVD251



6. Packing capacity & dimension

Dimension				
Dimension	78.00mm diameter * 13.60mm height			
Net Weight	43g			
Packing Capacity				
Model	Dimensions	Layer	Quantity/Layer	Quantity(Pcs)
Carton1:	430mm(L)×335mm(W)×290mm(H)	7	12	84

DMG48480F021_01WTCZG2 Installation Schematic

1

The back of the screen shell is equipped with 3 buckles, with the middle section marked '△' to indicate the correct installation orientation.

2

The opening requirements are shown in the figure.
Depth > 15.0mm
Device front housing thickness < 3.0mm

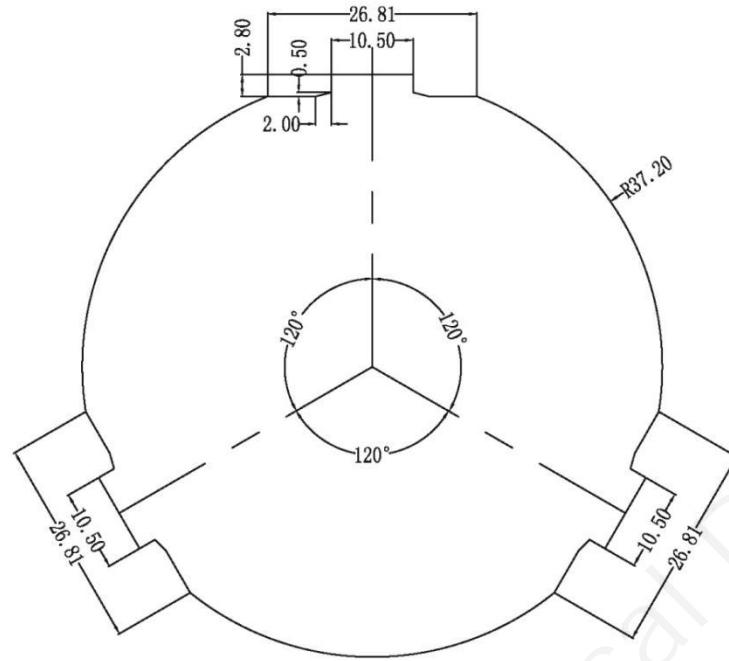
Align the screen with the cut-out area and gently push it in with your fingers until hear a 'click', confirming the buckles are securely fastened.

3

The final effect

Note:

- Smooth Insertion: Since the internal structure may not be visible during installation, push the buckles gently to avoid damaging them.
- Secure Check: After insertion, ensure that all buckles are fully engaged to guarantee a stable and secure lock onto the device panel.



DMG48480F021_01WTCZG2 Frame Opening Dimensions for Users

Note: Chamfers are required at the sharp corners of the slots, and for the chamfer dimensions, please refer to the above picture.

7. Revision records

Rev	Revise Date	Content	Editor
00	2025-02-21	First Edition	Xu Ying

Please contact us if you have any questions about the use of this document or our products, or if you would like to know the latest information about our products:

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